

PATENT ABSTRACTS OF JAPAN

(11) Publication number : 10-270445
(43) Date of publication of application : 09.10.1998

(51) Int.CI.

H01L 21/3205
H01L 21/768

(21) Application number : 09-076167
(22) Date of filing : 27.03.1997

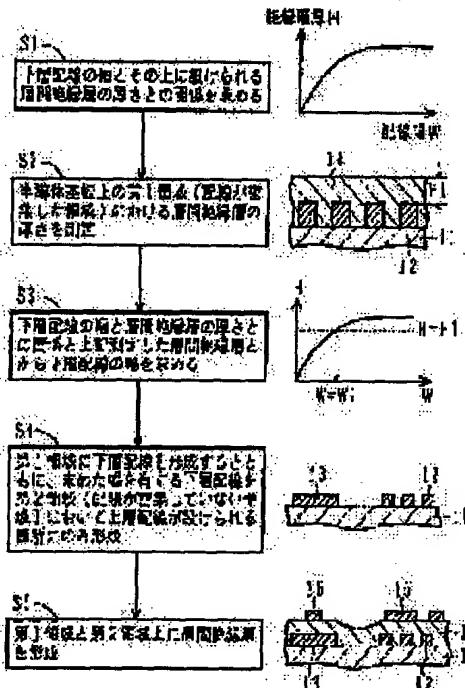
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(54) SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF

(57) Abstract:

PROBLEM TO BE SOLVED: To have a multi-layer interconnection structure forming an upper layer wirings on a substantially flat insulation layer surface by measuring the thickness of a layer insulation film having a planarizing function at close wiring regions and selecting the width of a lower layer dummy wiring below an upper layer isolated wiring corresponding to the measured thickness.

SOLUTION: The manufacturing method comprises step S1 of obtaining the relation between the width of a lower layer dummy wiring and thickness of a layer insulation film having a planarizing function thereon, step S2 of forming the layer insulation film on first close wiring regions on a semiconductor substrate under specified condition and measuring its thickness, step S3 of determining the dummy wiring width W at isolated regions so that the thickness M1 of the layer insulation film is equal to that at the isolated regions, step S4 of forming a lower layer wiring at the first regions and lower layer dummy wiring of the width W at the second isolated regions where wirings are not close, and forming a layer insulation film 14 on the surface including the first and second regions and upper layer wirings 15, 16 thereon.



LEGAL STATUS

[Date of request for examination] 02.12.1998

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number] 3159108

[Date of registration] 16.02.2001

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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